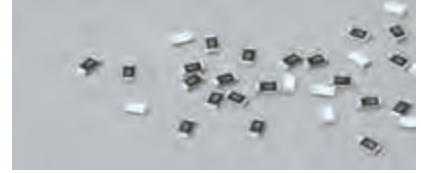
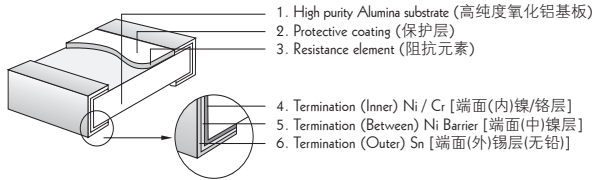
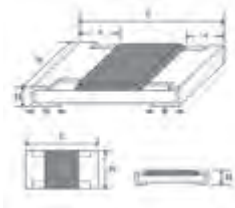


Feature (特性)

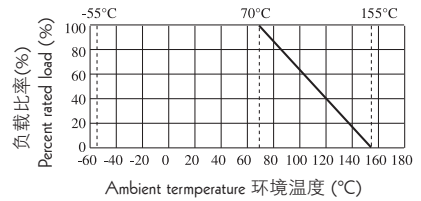
- Suitable for reflow & wave soldering (适合波峰焊与回流焊)
- Application Soft Circuit board (适用于软性电路板)



Figures (型状)



Derating Curve (降功率曲线)



Specification (性能)

Type 类型	Max working voltage 最大工作电压	Max Overload Voltage 最大过负荷电压	Dielectric Withstanding Voltage 绝缘耐压	Operating Temperature 工作温度范围
LE03	75V	150V	300V	-55~+155°C
LE05	150V	300V	500V	-55~+155°C
LE06	200V	400V	500V	-55~+155°C

Type 类型	Power 功率 (70°C)	L (mm)	W (mm)	H (mm)	A (mm)	B (mm)	Resistance Range 阻值范围 0.5%, 1%, 5%
LE03	1/16W (1/10W-S)	1.60±0.10	0.80±0.10	0.45±0.10	0.30±0.20	0.30±0.20	1Ω~10M 0Ω
LE05	1/10W (1/8W-S)	2.00±0.15	1.25 ^{+0.15} _{-0.10}	0.55±0.10	0.40±0.20	0.40±0.20	1Ω~10M 0Ω
LE06	1/8W (1/4W-S)	3.10±0.15	1.55 ^{+0.15} _{-0.10}	0.55±0.10	0.45±0.20	0.45±0.20	1Ω~10M 0Ω

Performance Specification (性能)

Temperature coefficient 温度系数	1Ω~10Ω: ≤±400ppm / °C 11Ω~100Ω: ≤±200ppm / °C > 100Ω: ≤±100ppm / °C
Short-time overload 短时间过负荷	±5%, ±2%: ±(2.0%+0.1Ω)Max. (最大) ±1%, ±0.5%: ±(1.0%+0.1Ω)Max. (最大)
Terminal bending 端子弯曲	±(1.0%+0.05Ω)Max. (最大)
Solderability 可焊性	Min. 95% Coverage (最少 95% 覆盖率)
Soldering heat 耐焊接热	±(1.0%+0.05Ω) Max. (最大)
Humidity (Steady State) 恒定湿热	±5%, ±2%: ±(3.0%+0.1Ω)Max. (最大) ±1%, ±0.5%: ±(0.5%+0.1Ω)Max. (最大)
Dielectric withstanding voltage 绝缘耐压	No evidence of flashover, mechanical damage, arcing or insulation breakdown 无击穿, 飞弧及可见机械性损伤
Temperature Cycling 温度循环	±5%, ±2%: ±(1.0%+0.05Ω)Max. (最大) ±1%, ±0.5%: ±(0.5%+0.05Ω)Max. (最大)
Load life 负载寿命	±5%, ±2%: ±(3.0%+0.1Ω)Max. (最大) ±1%, ±0.5%: ±(1.0%+0.1Ω)Max. (最大)

Ordering Procedure (Example: LE06 1/4W-S 5% 1.2 Ω T/R-5000)

订购方式 (例如: LE06 1/4W-S 5% 1.2 Ω T/R-5000)

